Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.6 EP)
Lead Count	16
Terminal Finish	100 Sn
MS Number	MS010587B

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.18E-02	86.91	869100	31.88	318790
Thermosets	Epoxy & Phenol Resin	Proprietary	1.73E-03	12.78	127800	4.69	46878
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.31	3100	0.11	1137
Subtotal			1.35 E-02	100.00	1000000	36.68	366805

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.88 E-02	97.5	975000	51.01	510089
Copper & its alloys	Iron	7439-89-6	4.54 E-04	2.35	23500	1.23	12294
Copper & its alloys	Zinc	7440-66-6	2.32 E-05	0.12	1200	0.06	628
Copper & its alloys	Phosphorus	7723-14-0	5.79 E-06	0.03	300	0.02	157
Subtotal			1.93 E-02	100.00	1000000	52.32	523168

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.97 E-04	100.0	1000000	1.08	10767

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	5.69 E-04	100.0	1000000	1.54	15416

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	3.22 E-04	99.0	990000	0.87	8721
Precious metals	Palladium	7440-05-3	3.25 E-06	1.0	10000	0.01	88
Subtotal			3.25 E-04	100.0	1000000	0.88	8809

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.17 E-03	100.0	1000000	5.87	58728

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.70 E-04	77.71	777100	1.27	12740
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Butyrolactone, gamma-	96-48-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Organosilane	TS ref# 10001	1.88 E-05	3.11	31100	0.05	510
Other inorganic materials	Copper(II) oxide	1317-38-0	1.88 E-05	3.11	31100	0.05	510
Other organic materials	Epoxy resin modifier	TS ref# 10038	3.15 E-06	0.52	5200	0.009	85
Subtotal			6.05 E-04	100.0	1000000	1.64	16395

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.6 EP)
Lead Count	16
Terminal Finish	NiPdAu
MS Number	MS012146A

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.38E-02	88.00	880000	37.30	372956
Thermosets	Epoxy & Phenol resin	Proprietary	1.80E-03	11.50	115000	4.87	48739
Other inorganic materials	Carbon black	1333-86-4	7.82E-05	0.50	5000	0.21	2119
Subtotal			1.56E-02	100.00	1000000	42.38	423813

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.17 E-02	97.50	975000	31.77	317716
Copper & its alloys	Iron	7439-89-6	2.83 E-04	2.35	23500	0.77	7658
Copper & its alloys	Zinc	7440-66-6	1.44 E-05	0.12	1200	0.04	391
Copper & its alloys	Phosphorus	7723-14-0	3.61 E-06	0.03	300	0.01	98
Subtotal			1.20 E-02	100.00	1000000	32.59	325863

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	5.17 E-05	97.27	972697	0.14	1401
Precious metals	Palladium	7440-05-3	1.20 E-06	2.26	22621	0.00	33
Precious metals	Gold	7440-57-5	2.49 E-07	0.47	4683	0.001	7
Subtotal			5.31 E-05	100.00	1000000	0.14	1440

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.68 E-05	99.00	990000	0.07	727
Precious metals	Palladium	7440-05-3	2.71 E-07	1.00	10000	0.001	7
Subtotal			2.71 E-05	100.00	1000000	0.07	735

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	6.56 E-03	100.0	1000000	17.78	177771

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	2.00 E-03	77.00	770000	5.42	54191
Other organic materials	Acrylic resin	Proprietary	1.82 E-04	7.00	70000	0.49	4926
Other organic materials	Acrylate	Proprietary	1.43 E-04	5.50	55000	0.39	3871
Other organic materials	Polybutadiene derivative	Proprietary	1.17 E-04	4.50	45000	0.32	3167
Thermoset	Epoxy resin	Proprietary	6.49 E-05	2.50	25000	0.18	1759
Other organic materials	Butadiene Copolymer	Proprietary	3.90 E-05	1.50	15000	0.11	1056
Others	Additive	Proprietary	3.90 E-05	1.50	15000	0.11	1056
Others	Peroxide	Proprietary	1.30 E-05	0.50	5000	0.04	352
Subtotal			2.60 E-03	100.0	1000000	7.04	70378

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.69 E-02**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary